

ABSTRACT OF THE INVENTION

OPTICAL SENSOR PACKAGE

An image sensor device includes a QFN type leadframe having a central die attach flag and an outer bonding pad area having a plurality of bonding pads. A sensor IC is attached to the flag. The IC has a first surface with an active area and a peripheral bonding pad area that includes bonding pads. Wires are wirebonded to respective ones of the IC bonding pads and corresponding ones of the leadframe bonding pads, thereby electrically connecting the IC and the leadframe. Stud bumps are formed on the first surface of the IC and a transparent cover is disposed over the IC active area and resting on the stud bumps. The cover allows light to pass therethrough onto the IC active area. A mold compound is formed over the leadframe, wirebonds and a peripheral portion of the cover.